SAMSUNG ELECTRO-MECHANICS

Ver. 201306

Multilayer Power Inductor

CIG10F Series (1608/ EIA 0603)

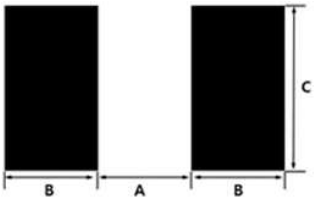
APPLICATION

Mobile DSC, DVC, PDA etc. for DC-DC Converter

FEATURES

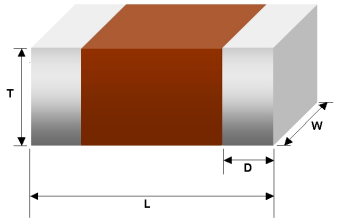
- The smallest multilayer power inductor (1.6mm×0.8mm)
- Much lower Profile than any other series (0.5mm max)
- Low DC resistance
- Magnetically shielded structure
- Free of all RoHS-regulated substances
- Monolithic structure for high reliability

RECOMMENDED LAND PATTERN



	1608
A	0.70㎜
B	0.70㎜
C	0.80㎜

DIMENSION



TYPE	Dimension [mm]			
	L	W	T	D
10	1.6±0.15	0.8±0.15	0.5 max.	0.3±0.2

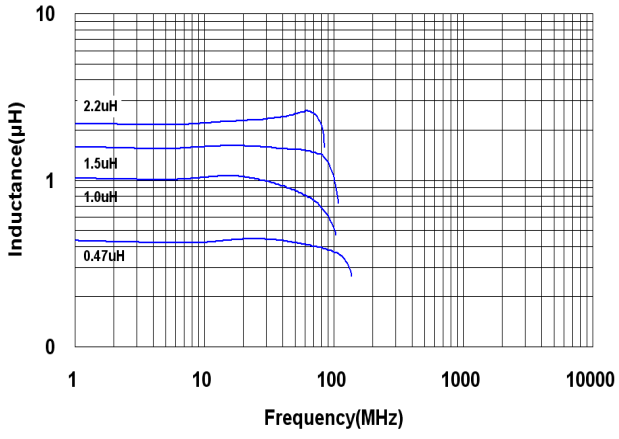
DESCRIPTION

Part no.	Size (inch/mm)	Inductance (uH)@1MHz	DC Resistance(Ω)	Rated Current (A) Max.
CIG10FR47MNC	0603/1608	0.47±20%	0.20±30 %	0.80
CIG10F1R0MNC	0603/1608	1.0±20%	0.30±30 %	0.70
CIG10F1R5MNC	0603/1608	1.5±20%	0.35±30 %	0.60
CIG10F2R2MNC	0603/1608	2.2±20%	0.45±30 %	0.50

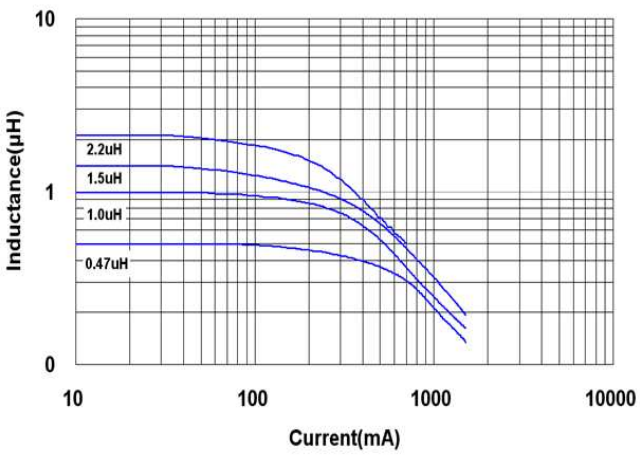
※Rated Current: DC current value when the self-generation of heat rises to 40℃ (Reference ambient temperature:25℃)
※Operating temperature range: –40 to +125℃ (Including self-temperature rise)
※Test equipment: Agilent :E4991A+16092A

CHARACTERISTIC DATA

1) Frequency characteristics (Typ.)



2) DC Bias characteristics (Typ.)



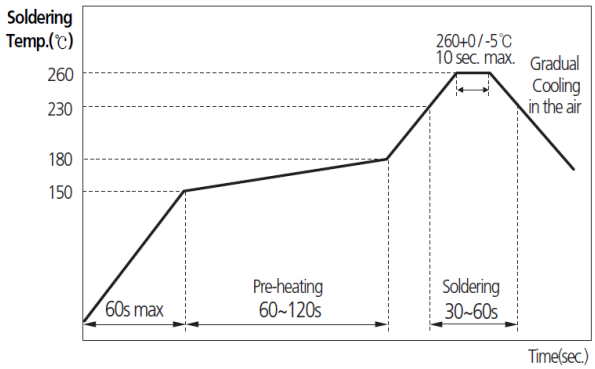
PRODUCT IDENTIFICATION

CI	G	10	F	2R2	M	N	C
(1)	(2)	(3)	(4)	(5)	(6)	(7)	(8)

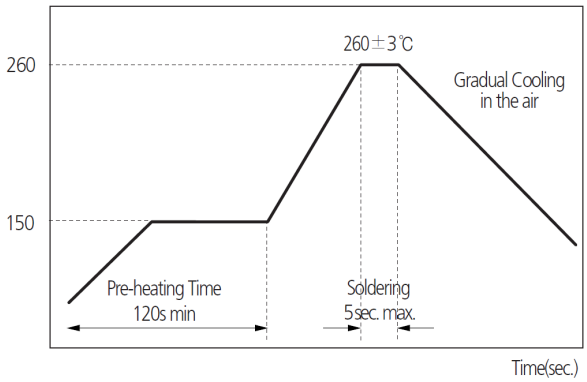
(1) Chip Inductor
(2) Power Inductor
(3) Dimension
(4) Product Series (F:Low Profile Type)
(5) Inductance (R47:0.47uH, 2R2:2.2uH)
(6) Tolerance (M:±20%)
(7) Thickness option(N:Standard, A:Thinner than standard, B:Thicker than standard)
(8) Packaging(C:paper tape, E:embossed tape)

RECOMMENDED SOLDERING CONDITION

REFLOW SOLDERING



FLOW SOLDERING



PACKAGING

Packaging Style	Quantity(pcs/reel)
Card Board Taping	4,000